

Abstract of the Disclosure:

In a method of bonding components, a poly-o-hydroxyamide is applied to each of the bond areas of the components to be bonded. After the bond areas have been bonded to one another  
5 the adhesively bonded assembly is heated in order to convert the poly-o-hydroxyamide to the corresponding polybenzoxazole. The adhesive bonding technology is able to replace conventional joining techniques, such as welding, brazing or shrink fitting. The method is especially suitable for  
10 producing X-ray image intensifiers.

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